

Sensors and Materials

Special Issue on Mechanical and Thermal Reliability of Micro/Nanomaterials

Call for Papers

Owing to the rapid progress of recent semiconductor fabrication technologies, precisely shaped mechanical and electrical components in semiconductor devices and micro-electromechanical systems (MEMS) can be produced. To improve their performance and reliability, the mechanical and thermal properties of structural materials at the micro/nanoscale should be measured experimentally, and then the knowledge obtained in experiments should be reflected in the design of these devices. This special issue will focus on state-of-the-art experimental technologies for measuring the mechanical and thermal properties of silicon and related materials.

Scope:

- mechanical and thermal properties
- silicon-related materials, metals, and polymers
- reliability of semiconductor devices and MEMS
- experimental technologies
- size effects and process effects

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Journal website: <http://myukk.org/>

Guest Editors: Prof. Takahiro Namazu (Aichi Institute of Technology) and Dr. Shugo Miyake (Kobe City College of Technology)

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